

Please add the following new claims to the application:

-- 5. An electronic component according to claim 1, wherein the conductor paste includes, in addition to silver, at least one selected from the group consisting of platinum and palladium.

6. An electronic component according to claim 5, wherein the at least one selected from the group consisting of platinum and palladium is included in the conductor paste in an amount sufficient to prevent silver migration and solder leaching.--